

Eternal PhotoResist Product List

<i>Product Type</i>	<i>Target Application</i>	<i>Series</i>	<i>Thickness</i>	<i>Proposed Application</i>
UV Type Dry Film Resist	Printed Circuit Board	HT	15 ~ 49 μm	Etching, Tenting , Plating
	Flexible Circuit Board	HP	15 ~ 38 μm	Etching, Tenting , Plating
	Packaging Boards (MCM, CSP, BGA)	HQ	15 ~ 100 μm	Etching (Acid & Alkali) ,Au Plating, ENIG
	Wafer Application	BR	100 ~ 320 μm	Bump Building
	Glass Surface Substrate	TPR	10 ~ 50 μm	Sand Blasting & ITO Metal Etching
LDI Type Dry Film Resist	Fine Circuit Printed Circuit Board	UD, UDF	20 ~ 49 μm	Etching, Plating

Nikko Material PhotoResist Product List

<i>Product Type</i>	<i>Target Application</i>	<i>Series</i>	<i>Thickness</i>	<i>Proposed Application</i>
UV Type Dry Film Resist	Printed Circuit Board - Rigid & Flex	202J	25 ~ 40 μm	Etching, Tenting with L/S down to 25 μm
	Fine Circuitry Flexible Printed Circuit Board	NIT	10 ~ 38 μm	Etching, Tenting , Plating
	Precision Metal Machining	NCP	25 ~ 50 μm	Etching & Tenting (Both SUS & special metals)
	FC CSP / FC BGA	A310 / 10A303D	10 ~ 35 μm	Subtractive & Semi Additive
	Glass Surface Substrate	TPR	10 ~ 50 μm	Sand Blasting & ITO Metal Etching
DI Type Dry Film Resist	FC CSP / FC BGA	LDF	15 ~ 25 μm	Etching & Plating (Both h- line & I-line)
	FPC / HDI	LIP	25 ~ 40 μm	Etching & Plating (Both h- line & I-line)